

**WEST**

Generate Collection

L2: Entry 20 of 33

File: DWPI

Oct 22, 1993

DERWENT-ACC-NO: 1993-372640

DERWENT-WEEK: 199347

COPYRIGHT 2001 DERWENT INFORMATION LTD

TITLE: Mfg. copper@ foil for printed circuit improving e.g. rust-proof characteristics - by forming on rough copper@ foil surface, zinc, and chromium-oxide coatings

PATENT-ASSIGNEE:

ASSIGNEE

CODE

NIKKO KYOSEKI KK

NIHA

PRIORITY-DATA: 1979JP-0164109 (December 19, 1979), 1992JP-0212355 (December 19, 1979)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 05275817 A	October 22, 1993	N/A	009	H05K001/09

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP05275817A	December 19, 1979	1979JP-0164109	Div ex
JP05275817A	December 19, 1979	1992JP-0212355	N/A

INT-CL (IPC): C23C 22/00; C23C 28/00; H05K 1/09

RELATED-ACC-NO: 1981-63506D

ABSTRACTED-PUB-NO: JP05275817A

BASIC-ABSTRACT:

Cu-foil is made by forming a Zn-coating of 15-1500 microgram/dm<sup>2</sup> coating weight ad Zn, and forming Cr-oxide coating of 15-30 microgram/dm<sup>2</sup> coating weight, as Cr, on a rough surface of the Cu-foil. Alternatively smooth lustrous surface of the Cu is treated with the exception of double coatings of Zn and Cr-oxide.

USE - For making Cu-foil for printed circuits, improving characterist ics e.g. rustproof characteristics needed for rough surface of the foils.

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	22374	(nickel WITH chromium with aluminum with silicon) or (Ni with Cr with Al with Si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 08:26	
2	BRS	L2	141	1 same foil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 09:00	
3	BRS	L3	45	2 and (Tantalum or Ta)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 09:02	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	25040	338/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:47	
2	BRS	L2	880	1 and foil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:48	